



USB467A

4.40-4.94GHz USB Series TDD Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for up to 5.0W at the antenna port.



Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	8.0 Watt max
Peak Input Power	-	-	-	80 Watt max
Input-Output Response				
Passband Insertion Loss (5 MHz avg)	4400 - 4940	0.8 dB	1.1 dB max	1.3 dB max
Passband Ripple	4400 - 4940	0.3 dB	0.7 dB max	0.7 dB max
Passband Return Loss	4400 - 4940	15 dB	14 dB min	14 dB min
Attenuation:	3688 - 3958	47 dB	45 dB min	45 dB min
	5382 - 7125	47 dB	45 dB min	45 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

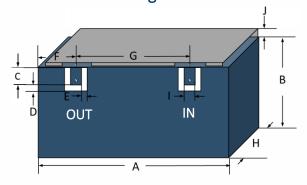
Specification Allowance					
Insertion Loss	0.1 dB				
Return Loss	1.0 dB				
Attenuation	1.0 dB				

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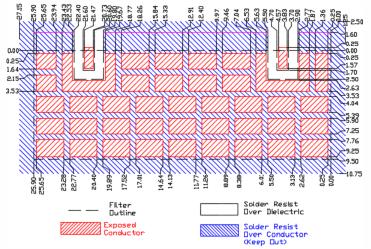




Mechanical Drawing

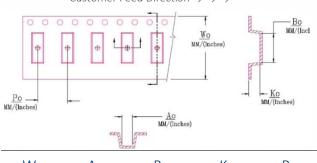


PCB Layout



Packaging and Marking

Dimension	Units	Spec.	Product Marking				
Reel Diameter	mm	330	CTS				
Reel Weight	kg	5.5	467				
Reel Quantity	ea.	500	YWW				
Customer Feed Direction $\rightarrow \rightarrow \rightarrow$							



W_{o}	A_{o}	Во	K _o	P_{o}
1.732 in	0.165 in	1.028 in	0.283 in	0.472 in
44.0 mm	4.20 mm	26.10 mm	7.20 mm	12.0 mm

Nominal Tolerance Dim. (±mm or Max) (mm) Α 25.40 0.50 2.70 0.20 В C 1.70 0.13 D 0.80 0.13 E 0.80 0.13 F 4.25 0.20 G 16.90 0.13 Н 6.70 max 1 1.00 0.13 1.10 0.20

IMPORTANT: Please assure >= 30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

NOTE: The width of 9.50mm is necessary to support frequencies as low as 1885MHz for Band 39. If only higher frequency TDD bands are supported, then a smaller space can be allocated on the layout.

Electrical Response

